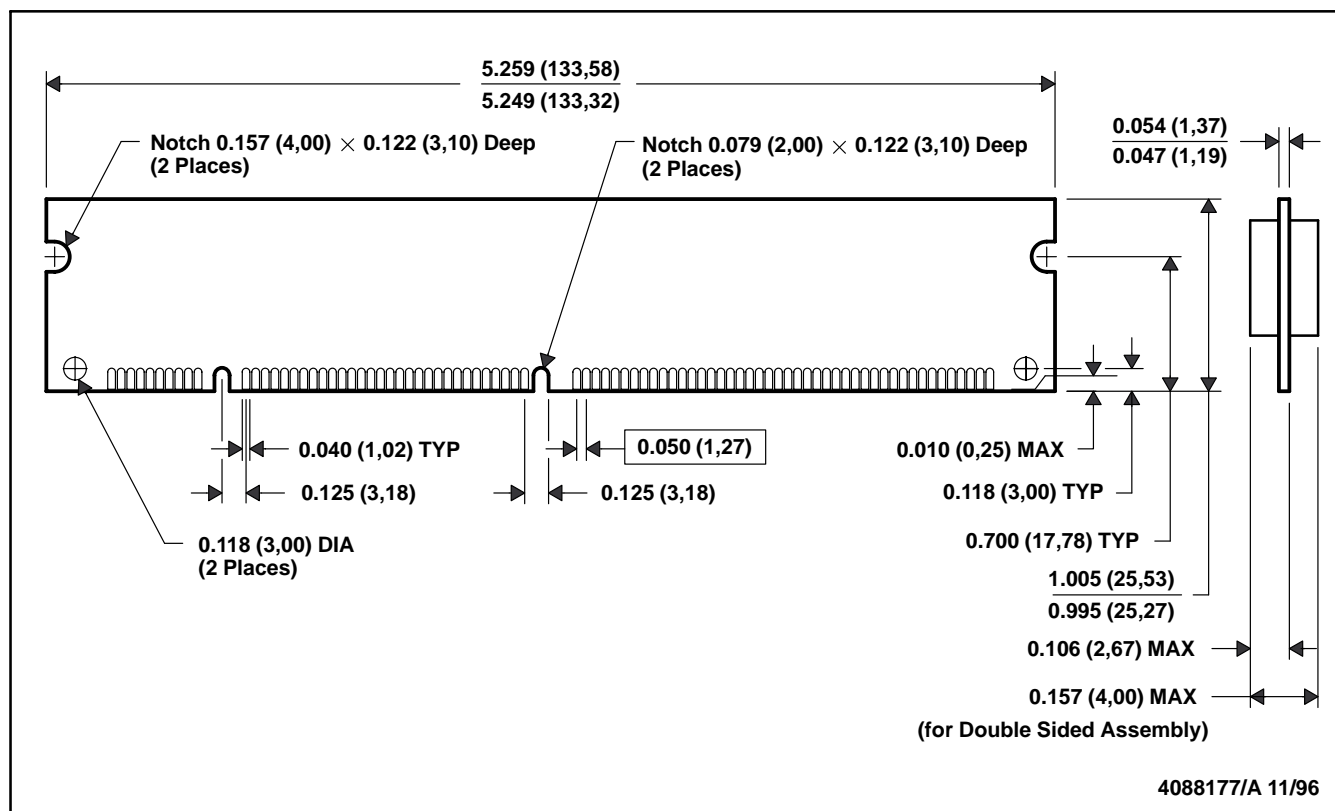


BQ (R-PSIP-N84)

DUAL-IN-LINE MEMORY MODULE



- NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MO-161

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